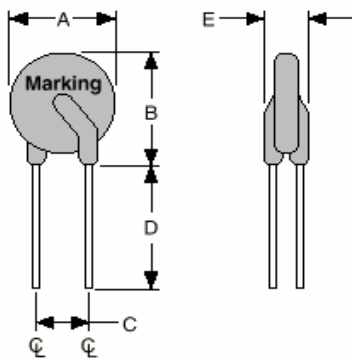


Features

- Radial leaded devices
- Cured, flame retardant epoxy polymer insulating material meets UL94 V-0 requirements
- Agency Recognition: UL, CSA, TUV
- Lead-free, halogen-free and compliant with the European Union RoHS Directive 2011/65/EU

Product Dimensions (mm)

A	B	C	D	E	Lead Size(φ)
Max.	Max.	Min.	Max.	Min.	Max.
13.0	18.0	4.4	5.8	7.6	3.1



Electrical Characteristics

I _H	I _T	T _{trip}	V _{max}	I _{max}	Pd _{typ}	R _{min}	R _{max}	R _{1max}
(A)	(A)	Current(A) Time(s)	(V)	(A)	(W)	(Ω)	(Ω)	(Ω)
1.10	2.20	5.50 8.2	60	40	1.51	0.14	0.25	0.38

I_H=Hold current: maximum current at which the device will not trip at 25°C still air.

I_T=Trip current: minimum current at which the device will always trip at 25°C still air.

T_{trip}=Maximum time to trip at 5 times hold current.

V_{max}=Maximum voltage device can withstand without damage at rated current.

I_{max}=Maximum fault current device can withstand without damage at rated voltage.

Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min}=Minimum device resistance at 25°C prior to tripping.

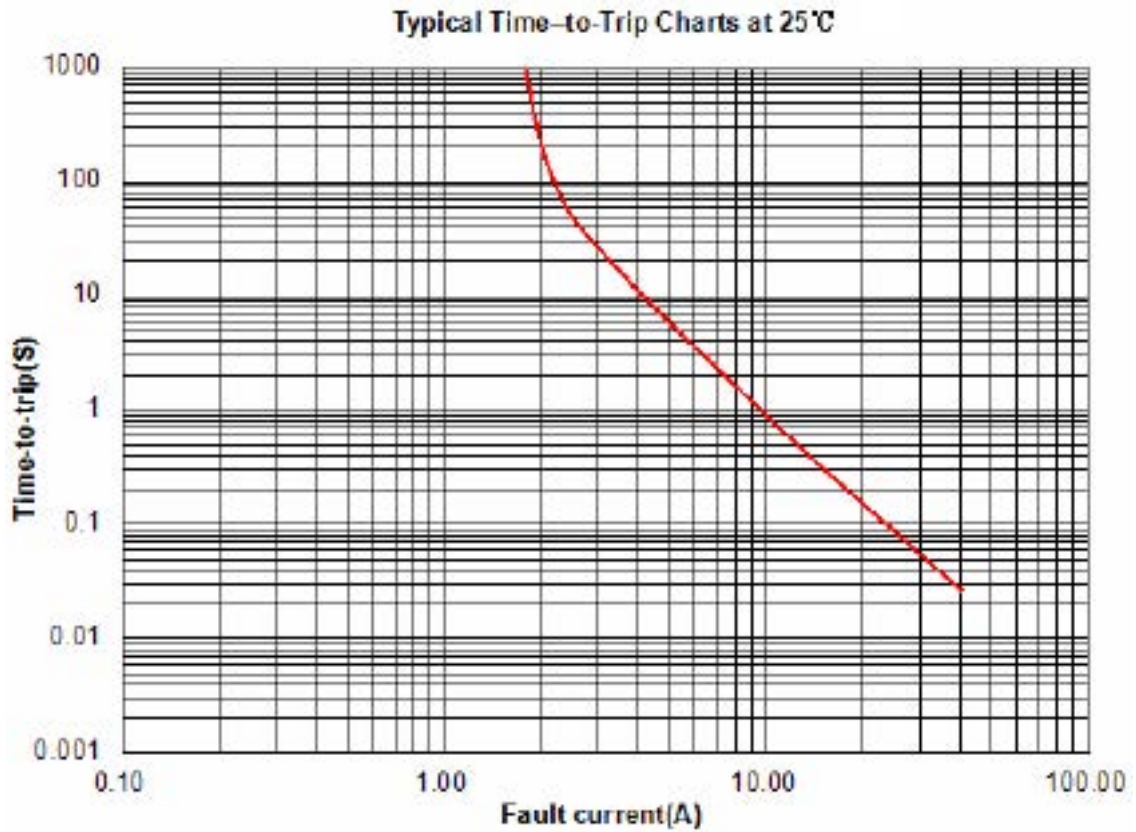
R_{max}=Maximum device resistance at 25°C prior to tripping.

R_{1max}= Maximum resistance of device when measured one hour post trip at 25°C.

Thermal Derating Chart- I_H(A) (Hold current at ambient temperature)

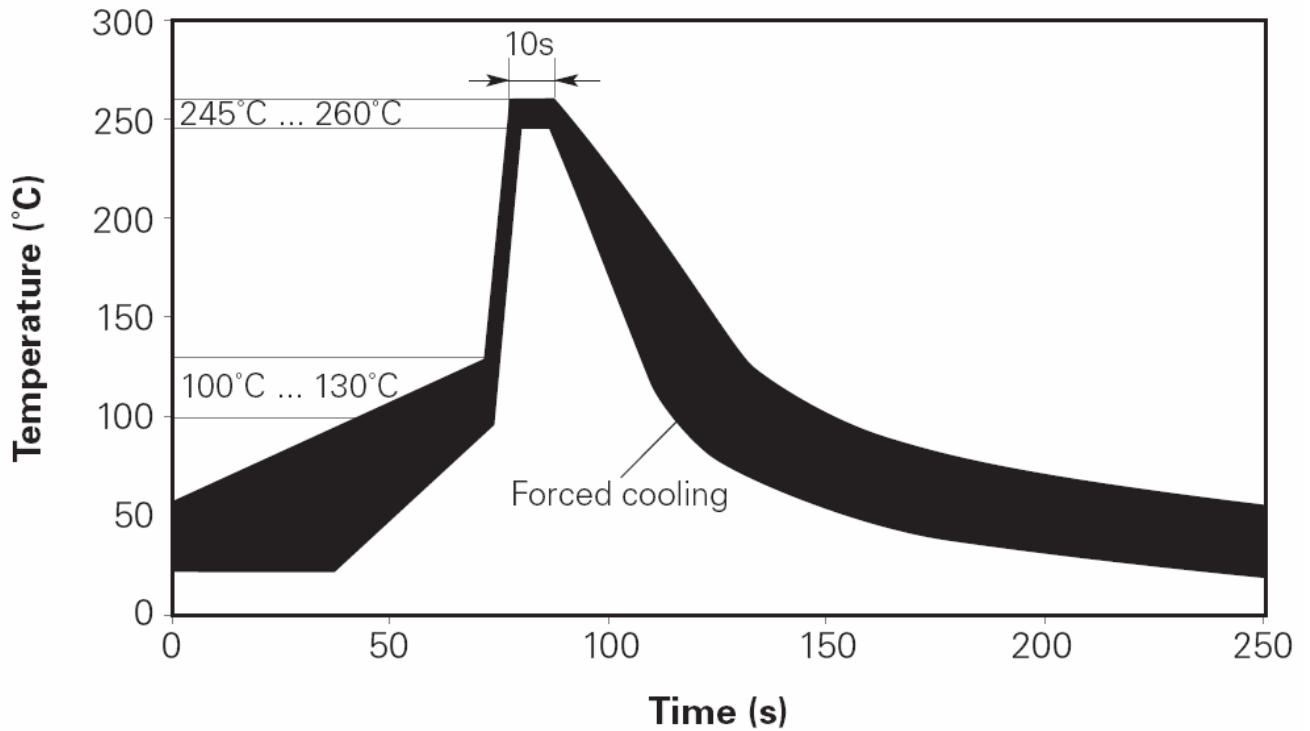
Maximum ambient operating temperature(°C)									
-40	-20	0	25	40	50	60	70	85	
1.82	1.60	1.35	1.10	0.89	0.79	0.65	0.55	0.40	

Typical Time-to-Trip Charts at 25°C



Soldering Recommendations

Wave Soldering



Hand Soldering

Soldering temperature: $350^{\circ}\text{C} \pm 5^{\circ}\text{C}$.

Soldering time: no more than 5s.

Soldering position: at least 4 mm away from PTC chip.